### **GENERAL DESCRIPTION**

The SGM2588 is an integrated  $100m\Omega$  (TYP) power switch for self-powered and bus-powered Universal Series Bus (USB) applications.

The SGM2588 is internally current limited and has thermal shutdown that protects device and load from over-current damage. Thermal shutdown shuts off the output MOSFET and asserts the  $\overline{FAULT}$  output if the die temperature exceeds 150°C until the die temperature drops to 130°C.

This device employs soft-start circuit that minimizes inrush current in applications where highly capacitive loads are employed.

An open drain  $\overline{FAULT}$  flag asserts low during overcurrent and thermal conditions after a 13ms blanking time to prevent false reporting.

SGM2588 is available in the Green SOT-23-5 package. It is rated over the -40°C to +85°C temperature range.

## **FEATURES**

- 100mΩ (TYP) High-side N-Channel MOSFET
- Three Current Limit Levels
  - SGM2588A/B/G: 1100 ± 100mA SGM2588C/D/I: 2100 ± 210mA SGM2588E/F/K: 2600 ± 300mA
- Input Voltage Range: 2.5V to 5.5V
- Low 23µA Quiescent Current
- Typical 0.1µA Shutdown Current
- Soft-Start Function
- Thermal Shutdown Protection
- Under-Voltage Lockout Protection for VIN
- No Reversed Leakage Current (Reverse Blocking)
- Fault Flag (FAULT) with 13ms Filter Eliminates False Assertions
- Automatic Output Discharge in Shutdown Mode (SGM2588A/B/C/D/E/F)
- 500kΩ Pull-Down Resistor at EN Pin (SGM2588G/I/K)
- Available in the Green SOT-23-5 Package

### **APPLICATIONS**

General Purpose Power Switching USB Bus/Self Powered Hubs/Peripherals ACPI Power Distribution Smart Phone & LCD TV



### **TYPICAL APPLICATION**

## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM2588A (Active High)	SOT-23-5	-40°C to +85°C	SGM2588AYN5G/TR	SSCXX	Tape and Reel, 3000
SGM2588B (Active Low)	SOT-23-5	-40°C to +85°C	SGM2588BYN5G/TR	SSDXX	Tape and Reel, 3000
SGM2588C (Active High)	SGM2588C SOT-23-5 -40°C to +		SGM2588CYN5G/TR	SSEXX	Tape and Reel, 3000
			SGM2588DYN5G/TR	ST0XX	Tape and Reel, 3000
			SGM2588EYN5G/TR	ST1XX	Tape and Reel, 3000
			SGM2588FYN5G/TR	ST2XX	Tape and Reel, 3000
SGM2588G (Active High)	SOT-23-5	-40°C to +85°C	SGM2588GYN5G/TR	G51XX	Tape and Reel, 3000
SGM2588I (Active High)	SOI-23-5 -40°C to +85°C		SGM2588IYN5G/TR	G52XX	Tape and Reel, 3000
			SGM2588KYN5G/TR	G53XX	Tape and Reel, 3000

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

#### **ABSOLUTE MAXIMUM RATINGS**

All Pins	6V
FAULT Current	25mA
Power Dissipation, $P_D \textcircled{O} T_A = 25^{\circ}C$	
SOT-23-5	0.3W
Package Thermal Resistance	
SOT-23-5, θ <sub>JA</sub>	280°C/W
SOT-23-5, θ <sub>JC</sub>	93°C/W
Junction Temperature	150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (Soldering, 10s)	260°C
ESD Susceptibility	
HBM	2000V
MM	400V

### **RECOMMENDED OPERATING CONDITIONS**

Input Voltage Range	2.5V to 5.5V
EN Voltage Range	0.3V to 5.5V
All Other Pins	0V to 5.5V
Junction Temperature Range	40°C to +125°C
Operating Temperature Range	40°C to +85°C

#### MARKING INFORMATION



```
Date code - Month ("A" = Jan. "B" = Feb. ··· "L" = Dec.)
Date code - Year ("A" = 2010, "B" = 2011 ···)
Chip I.D.
```

For example: SSCCA (2012, January)

#### **OVERSTRESS CAUTION**

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### **ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.

### **PIN CONFIGURATION**





### **PIN DESCRIPTION**

PIN	NAME	FUNCTION
1	VOUT	Output Voltage.
2	GND	Ground.
3	FAULT	Fault Flag. Active low, open-drain output. Indicates over-current or thermal shutdown conditions. Over-current condition must last longer than $t_D$ in order to assert FAULT.
4	EN/EN	Chip Enable. Do not floating for SGM2588A/B/C/D/E/F. Active HIGH for SGM2588A/C/E/G/I/K (EN) and active LOW for SGM2588B/D/F ( $\overline{EN}$ ). SGM2588G/I/K have integrated a 500k $\Omega$ pull-down resistor at EN PIN.
5	VIN	Power Input Voltage.

# **TEST CIRCUIT**



Figure 2. SGM2588 Test Circuit

# **ELECTRICAL CHARACTERISTICS**

 $(V_{IN} = 5V, T_A = 25^{\circ}C, unless otherwise noted.)$ 

PARAMETER		SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Input Voltage Range		V <sub>IN</sub>		2.5		5.5	V	
Quiescent Supply Curren	Quiescent Supply Current		Switch on, VOUT = open		23	35	μA	
Shutdown Supply Curren	t	I <sub>SD</sub>	Switch off, VOUT = open		0.1		μA	
Supply Leakage Current	(SGM2588A/B/C/D/E/F)	ILEAKAGE	Switch off, V <sub>OUT</sub> = 0V		0.1		μA	
Output Leakage Current	(SGM2588G/I/K)		Switch off, V <sub>OUT</sub> = 5V		0.1		μA	
		V <sub>IH</sub>	V <sub>IN</sub> = 2.5V to 5.5V	1.6			v	
Enable Input Threshold		VIL	V <sub>IN</sub> = 2.5V to 5.5V			0.4	V	
Enable Input Current (SG	GM2588A/B/C/D/E/F)	I <sub>EN</sub>	$V_{EN}$ = 0V to 5V		0.1		μA	
EN Pin Pull-Down Resist	EN Pin Pull-Down Resistor (SGM2588G/I/K)				500		kΩ	
Switch Resistance		R <sub>DS(ON)</sub>	I <sub>OUT</sub> = 500mA		100		mΩ	
Output Turn-On Delay Time		t <sub>on</sub>	$R_L$ = 10 $\Omega$ , $C_L$ = 1 $\mu$ F, Figure 3		2.3		ms	
Output Turn-Off Delay Time		t <sub>OFF</sub>	$R_L$ = 10 $\Omega$ , $C_L$ = 1 $\mu$ F, Figure 3		25		μs	
	SGM2588A/B/G		Ramped load	1000	1100	1200		
Current Limit Threshold	SGM2588C/D/I	I <sub>LIM</sub>	Ramped load	1890	2100	2310	mA	
	SGM2588E/F/K		Ramped load	2300	2600	2900	]	
Over-Current FAULT R	esponse Delay Time	t <sub>D</sub>	Apply $V_{OUT} = 0$ until FAULT is low		13		ms	
Under-Voltage Lockout T	hreshold	V <sub>UVLO</sub>	V <sub>IN</sub> rising		2.15	2.3	V	
Under-Voltage Lockout Threshold Hysteresis					0.1		V	
FAULT Output Resistance		R <sub>FAULT</sub>	$\overline{FAULT}$ is low and $I_{SINK} = 10mA$		20		Ω	
FAULT Leakage Current		IFAULT	FAULT is high		0.1		μA	
VOUT Shutdown Discharge Resistance (SGM2588A/B/C/D/E/F)		R <sub>DIS</sub>	Switch off		50		Ω	
Thermal Shutdown Temperature			T <sub>J</sub> increasing		150		°C	
Thermal Shutdown Hyste	eresis				20		°C	













### TIMING DIAGRAM



Figure 3. SGM2588A/C/E/G/I/K Switch Turn-On and Turn-Off Delay Times







Figure 5. SGM2588A/C/E/G/I/K Fault Timing: Output Reset by Removing Load

## FUNCTIONAL BLOCK DIAGRAM







Figure 7. SGM2588G/I/K Block Diagram

### FUNCTIONAL DESCRIPTION

#### Input and Output

VIN is the power supply connection to the logic circuitry and the drain of the MOSFET. VOUT is the source of the output MOSFET. In a typical circuit, current flows from VIN to VOUT toward the load. The output MOSFET and driver circuit are also designed to allow the MOSFET source to be externally forced to a higher voltage than the drain ( $V_{OUT}$ >V<sub>IN</sub>) when the switch is disabled.

#### **Thermal Shutdown**

Thermal shutdown is employed to protect device and load from damage. It shuts off the output MOSFET and asserts the  $\overrightarrow{FAULT}$  output, if the die temperature exceeds 150°C until the die temperature drops to 130°C.

#### Soft-Start

In order to eliminate the upstream voltage sag caused by the large inrush current during hot-plug events, the "soft-start" feature effectively isolates power supplies from such highly capacitive loads.

#### **Under-Voltage Lockout (UVLO)**

UVLO prevents the MOSFET switch from turning on until input voltage exceeds 2.15V (TYP). If input voltage drops below 2.05V (TYP), UVLO shuts off the MOSFET switch. Under-voltage detection functions only when the switch is enabled.

#### **Current Limiting and Short Protection**

The current limit circuit is designed to limit the output current to protect the upstream power supply. The typical current limit threshold is set internally to approximately 1.1A (SGM2588A/B/G), 2.1A (SGM2588C/D/I), 2.6A (SGM2588E/F/K). Under output short-circuit condition, the typical current limit folded back 75%. If SGM2588 keeps at over-current condition for a long time, the junction temperature may exceed 150°C, and over- temperature protection will shut down the output until temperature drops 130°C or limit (short) condition is removed.

#### **Reverse-Voltage Protection**

The reverse-voltage protection feature turns off the N-MOSFET switch whenever the output voltage exceeds the input voltage by 50mV (TYP). The SGM2588 keeps the N-MOSFET turned off until the output voltage is lower than the input voltage by 12mV (TYP) or the chip enable is toggled.

#### Fault Flag (FAULT)

The FAULT signal is an open-drain N-MOSFET output. FAULT is asserted (active low) when an over-current or thermal shutdown condition occurs. Figure 4 and Figure 5 depict typical timings.

In the case of an over-current condition,  $\overrightarrow{FAULT}$  will be asserted only after the response delay time ( $t_D$ ) has elapsed. This ensures that  $\overrightarrow{FAULT}$  is asserted only upon valid over-current conditions and that erroneous error reporting is eliminated.

For example, false over-current conditions can occur during hot-plug events when a highly capacitive load is connected and causes a high transient inrush current that exceeds the current limit threshold for up to 1ms. The  $\overline{FAULT}$  response delay time  $t_D$  is 13ms (TYP).

#### **Power Dissipation**

The device's junction temperature depends on several factors such as the load, PCB layout, ambient temperature, and package type. Equations that can be used to calculate power dissipation and junction temperature are found below:

$$P_{\rm D} = R_{\rm DS(ON)} \times I_{\rm OUT}^{2}$$

To relate this to junction temperature, the following equation can be used:

$$T_{J} = P_{D} \times \theta_{JA} + T_{A}$$

where:

 $T_J$  = junction temperature  $T_A$  = ambient temperature  $\theta_{JA}$  = the thermal resistance of the package

## **APPLICATION INFORMATION**

#### **Supply Filter Capacitor**

In order to prevent the input voltage drooping during hot-plug events, connect a ceramic capacitor ( $C_{IN}$ ) from VIN to GND. The  $C_{IN}$  is positioned close to VIN and GND of the device. However, higher capacitor values could reduce the voltage sag on the input further. Furthermore, an output short will cause ringing on the input without the input capacitor. It could destroy the internal circuitry when the input transient exceeds 6V which is the absolute maximum supply voltage even for a short duration.

If the upstream supply cable is long or the VIN transient exceeds 6V during the VOUT short, recommend adding a second filter capacitor (not less than  $47\mu$ F) at the upstream supply output terminal.

#### **Output Filter Capacitor**

Between VOUT and GND, connect a low-ESR  $10\mu$ F ceramic capacitor to meet the 330mV maximum drop requirement. Standard bypass methods should be used to minimize inductance and resistance between the bypass capacitor and the down-stream connector. This will reduce EMI and improve the transient performance. If long cables are connected to the output terminals, an anti-parallel schottky diode such as BAT54 is suggested to be placed in parallel with the output terminals to absorb the negative ringing due to the cable inductance.

#### **PCB Layout Guide**

For best performance of the SGM2588, the following guidelines must be strictly followed:

- Keep all V<sub>BUS</sub> traces as short and wide as possible and use at least 2 ounce copper for all V<sub>BUS</sub> traces.
- Place a ground plane under all circuitry to lower both resistance and inductance and improve DC and transient performance.
- Dual low-ESR 10µF ceramic capacitors between VOUT and GND, VIN and GND.
- Locate the output capacitor as close to the connectors as possible to lower impedance (mainly inductance) between the port and the capacitor and improve transient performance.
- Input and output capacitors should be placed closed to the IC and connected to ground plane to reduce noise coupling.
- Locate the ceramic bypass capacitors as close as possible to the VIN pin and VOUT pin of SGM2588.

# PACKAGE OUTLINE DIMENSIONS

# SOT-23-5





RECOMMENDED LAND PATTERN (Unit: mm)





Symbol		nsions meters	Dimensions In Inches		
-	MIN	MAX	MIN	MAX	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	BSC	0.037	BSC	
e1	1.900 BSC		0.075	BSC	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

## TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT-23-5	7″	9.5	3.2	3.2	1.4	4.0	4.0	2.0	8.0	Q3

### **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

### **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton	
7" (Option)	368	227	224	8	
7"	442	410	224	18	DD0002